

Appl. No. 09/682,043
Amdt. Dated Oct. 07/2004
Reply to Office action of July 09, 2004

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (cancelled)

Claim 2 (new): A Thermodynamic Simulated Annealing Schedule to ease Simulated Annealing application in solving the Integrated Circuit placement problem.

Claim 3 (new): The Thermodynamic Simulated Annealing Schedule of Claim 1 consisting of computing the temperature after each iteration or local transformation by means of two alternative cases:

- a) Temperature is equal to an arbitrary positive initial value while either the accumulated cost variation is positive or the accumulated entropy variation is different from zero.
- b) Otherwise, temperature is equal to the run-time/quality tradeoffs parameter multiplied by the accumulated cost variation and divided by the accumulated entropy variation.